

Most Frequently Occurring Classifications of Patents Returned  
From A Search of 10/697,318 on February 18, 2005

Combined Classifications

9 257/E21.511	2 257/E21.506
7 257/E23.067	2 257/E21.526
6 257/778	2 257/E21.705
6 257/786	2 257/E23.065
6 257/E23.008	2 257/E23.068
6 257/E23.021	2 257/E23.069
6 257/E23.172	2 257/E23.08
6 438/106	2 257/E23.178
5 257/E23.079	2 257/E25.013
5 257/E25.012	2 257/E25.017
5 438/118	2 324/755
4 257/700	2 324/765
4 257/737	2 361/748
4 257/738	2 361/764
4 257/784	2 361/767
4 257/E23.177	2 361/783
4 257/E25.011	2 361/784
4 438/108	2 438/114
3 29/840	2 438/123
3 257/668	2 438/127
3 257/701	
3 257/723	
3 257/725	
3 257/E21.503	
3 257/E21.508	
3 257/E23.004	
3 257/E23.055	
3 257/E23.078	
3 257/E23.173	
3 361/760	
3 438/107	
3 438/125	
3 438/612	
3 438/613	
2 29/832	
2 174/260	
2 174/262	
2 257/666	
2 257/684	
2 257/686	
2 257/687	
2 257/691	
2 257/692	
2 257/712	
2 257/724	
2 257/726	
2 257/730	
2 257/739	
2 257/773	
2 257/E21.505	

- 6 257/778 (2 OR, 4 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD  
 257/778 .Flip chip
- 6 257/786 (0 OR, 6 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD  
 257/786 .Configuration or pattern of bonds
- 6 257/E23.008 (0 OR, 6 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)  
 257/E23.003 .Mountings, e.g., nondetachable insulating substrates (EPO)  
 257/E23.005 ..Characterized by material or its electrical properties (EPO)  
 257/E23.008 ...Semiconductor insulating substrates (EPO)
- 6 257/E23.021 (0 OR, 6 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)  
 257/E23.01 .Arrangements for conducting electric current to or from solid-state body in operation, e.g., leads, terminal arrangements (EPO)  
 257/E23.012 ..Consisting of lead-in layers inseparably applied to semiconductor body (EPO)  
 257/E23.019 ...Consisting of layered constructions comprising conductive layers and insulating layers, e.g., planar contacts (EPO)  
 257/E23.021 ....Bump or ball contacts (EPO)
- 6 257/E23.172 (0 OR, 6 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.139 ...Liquid at normal operating temperature of device (EPO)  
 257/E23.141 .Arrangements for conducting electric current within device in operation from one component to another, interconnections, e.g., wires, lead frames (EPO)  
 257/E23.169 ..Interconnection structure between plurality of semiconductor chips being formed on or in insulating substrates (EPO)  
 257/E23.172 ...Assembly of plurality of insulating substrates (EPO)
- 6 438/106 (3 OR, 3 XR)  
 Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS  
  
 438/106 PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING, ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR
- 5 257/E23.079 (0 OR, 5 XR)  
 Class 257 : ACTIVE SOLID-STATE DEVICES  
 257/E23.001 PACKAGING, INTERCONNECTS, AND MARKINGS FOR

SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES (EPO)

257/E23.01       ..Arrangements for conducting electric current  
to or from solid-state body in operation, e.g., leads,  
terminal arrangements (EPO)

257/E23.079       ..For integrated circuit devices, e.g., power  
bus, number of leads (EPO)

5 257/E25.012 (0 OR, 5 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/E25.001       ASSEMBLIES CONSISTING OF PLURALITY OF  
INDIVIDUAL SEMICONDUCTOR OR OTHER SOLID-STATE DEVICES

(EPO)

257/E25.002       ..All devices being of same type, e.g.,  
assemblies of rectifier diodes (EPO)

257/E25.003       ..Devices not having separate containers (EPO)

257/E25.01        ...Device consisting of plurality of  
semiconductor or other solid state devices or components  
formed in or on common substrate, e.g., integrated circuit  
device (EPO)

257/E25.012       ....Devices being arranged next to each other  
(EPO)

5 438/118 (1 OR, 4 XR)

Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/106           PACKAGING (E.G., WITH MOUNTING, ENCAPSULATING,  
ETC.) OR TREATMENT OF PACKAGED SEMICONDUCTOR

438/118           ..Including adhesive bonding step

PLUS Search Results for S/N 10/697318, Searched February 18, 2005 (Top 50)

The Patent Linguistics Utility System (PLUS) is a USPTO automated search system for U.S. Patents from 1971 to the present. PLUS is a query-by-example search system which produces a list of patents that are most closely related linguistically to the application searched. This search was prepared by the staff of the Scientific and Technical Information Center, SIRA.

6127833	4918811	RE35119	5946552	5659952
6228548	5055907	6004867	6072236	5677569
4802062	5923080	6091140	6114751	5682064
5401689	6323058	4965653	6121070	5798565
5192716	6506627	5191224	6144101	5897337
5342999	6768210	5252507	6228675	5933713
5629838	4907062	5309011	6228687	5982018
5977641	4902606	5315130	4866507	6103554
6153448	4924353	5514884	4989063	6108210
4783695	4937653	5691949	5539186	6114763